



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260122001.1

**Qualification of RFAB using qualified Process Technology for select devices
Change Notification / Sample Request**

Date: January 23, 2026

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260122001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA1654AIPWR	NULL
OPA1679IRUMT	NULL
OPA1679IPWR	NULL
OPA1679IRUMR	NULL
OPA1654AID	NULL
OPA1654AIDR	NULL
OPA1679IDR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260122001.1	PCN Date:	January 23, 2026
Title:	Qualification of RFAB using qualified Process Technology for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	April 23, 2026	Sample requests accepted until:	March 24, 2026*

***Sample requests received after March 24, 2026 will not be supported.**

Change Type:

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the 50HPA07HV qualified process technology for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DMOS5	50HPA07HV	200 mm	RFAB	50HPA07HV	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS5	DM5	USA	Dallas
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected			
OPA1654AID	OPA1654AID	OPA1654IRUMT	OPA1679IPWRG4
OPA1654AIDR	OPA1654AIDR	OPA1679IDR	OPA1679IRUMR
OPA1654AIDRG4	OPA1654AIDRG4	OPA1679IPWR	OPA1679IRUMT

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OPA1654AIDR	Qual Device: OPA1679IDR	Qual Device: OPA1679IRUMR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: INA231BIYFDR	QBS Process Reference: DRV401AIRGWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	3/231/0	2/154/0	-
HTOL	B1	Life Test	140C	480 Hours	-	-	-	1/77/0	2/154/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	2/154/0	2/154/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	1/1000/0	2/2000/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	2/2000/0	-
ESD	E2	ESD CDM	-	200 Volts	-	-	-	-	3/9/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-	2/6/0
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	-	2/6/0	-

Type	#	Test Name	Condition	Duration	Qual Device: OPA1654AIDR	Qual Device: OPA1679IDR	Qual Device: OPA1679IRUMR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: INA231BIYFDR	QBS Process Reference: DRV401AIRGWR
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	3/9/0	3/9/0	2/6/0	2/6/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	3/9/0	3/9/0	2/12/0	2/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0	1/30/0	2/60/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	1/Pass	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device OPA1654AIDR is qualified at MSL2 260C
- Qual Device OPA1679IDR is qualified at MSL2 260C
- Qual Device OPA1679IRUMR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2506-041

For alternate parts with similar or improved performance, please visit the product page on TI.com

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and

assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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